

FIG. 1

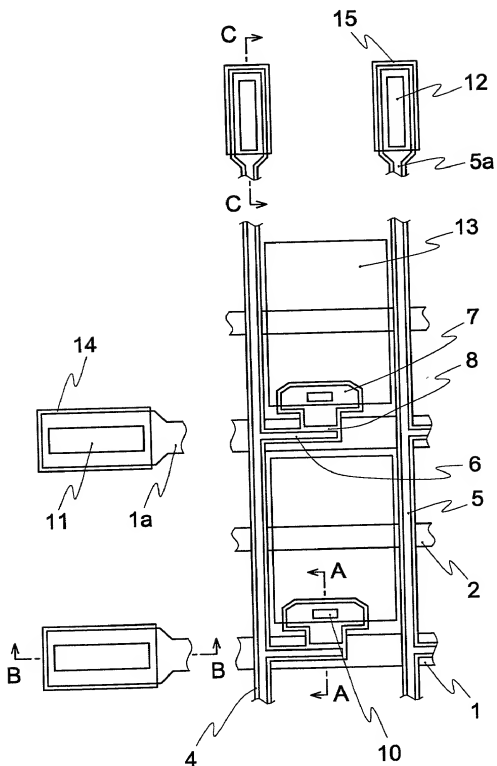


FIG. 2(a)

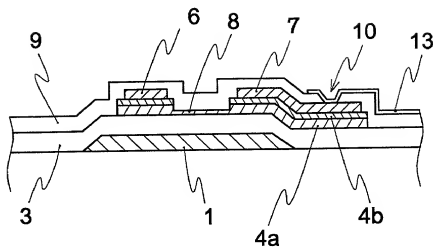


FIG. 2(b)

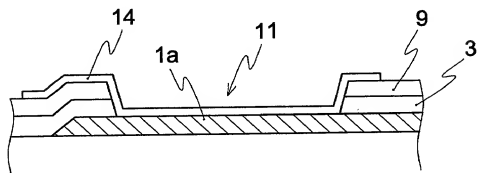


FIG. 2(c)

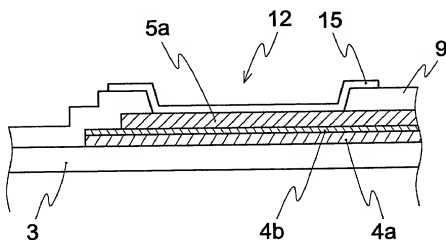


FIG. 2(d)

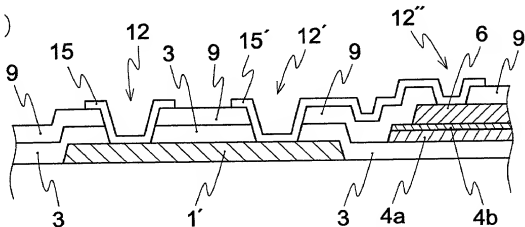


FIG. 3

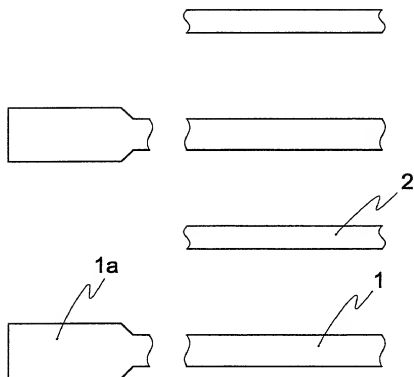


FIG. 4

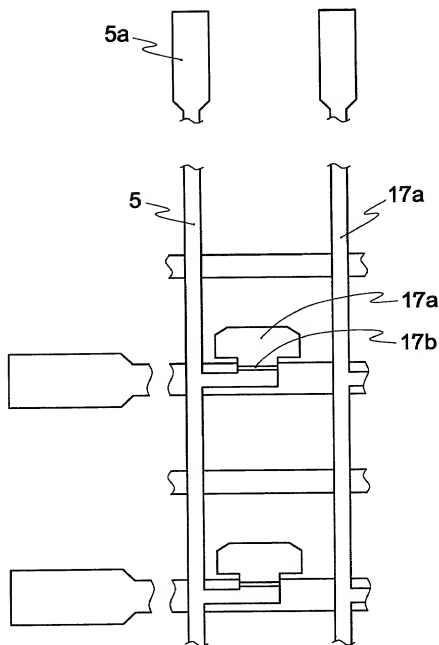


FIG. 5

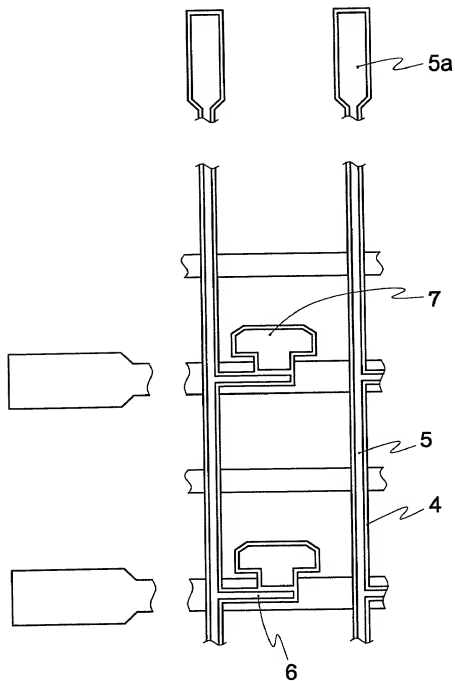


FIG. 6

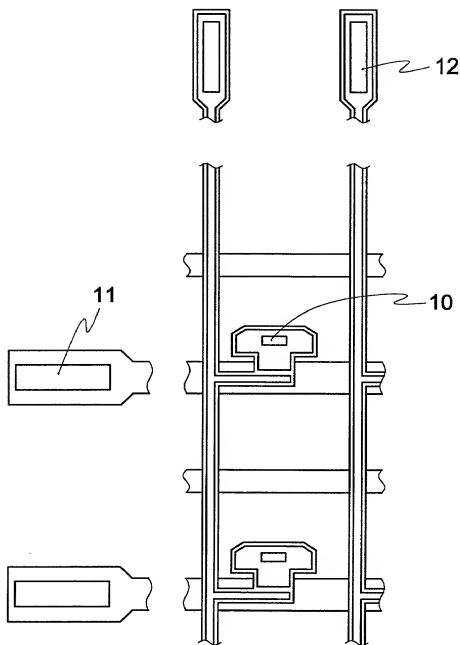


FIG. 7

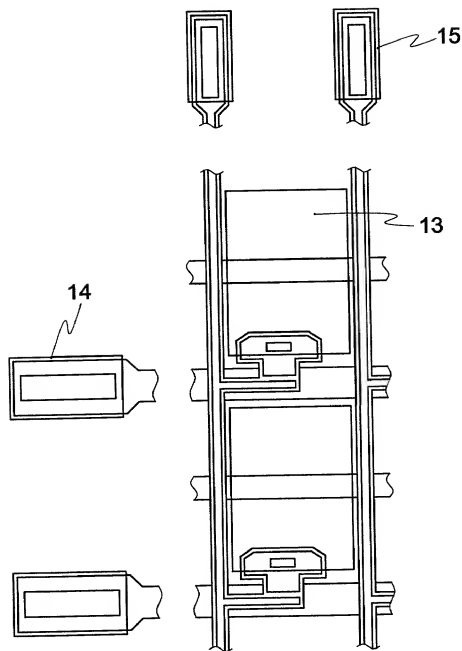


FIG. 8

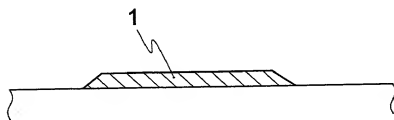


FIG. 9

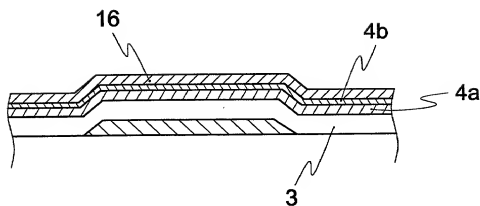


FIG. 10

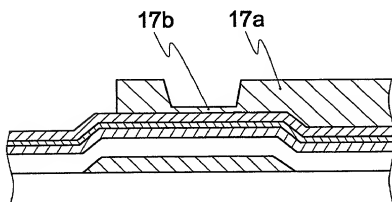


FIG. 11

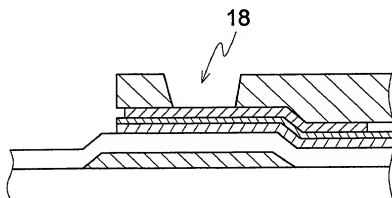




FIG. 12

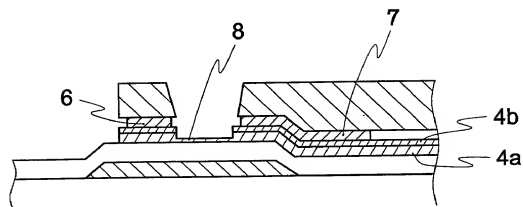


FIG. 13

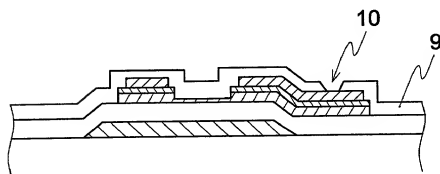


FIG. 14

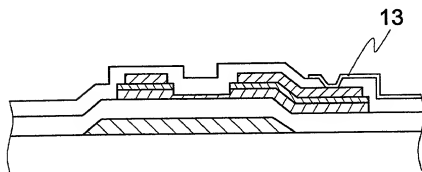


FIG. 15

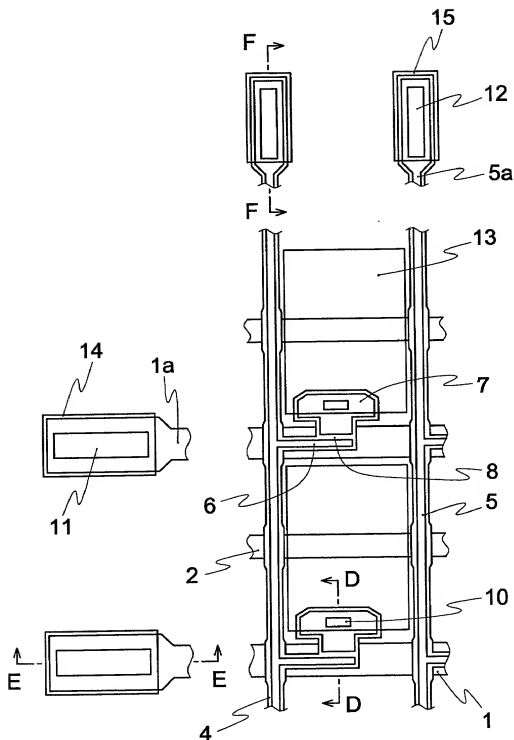


FIG. 16

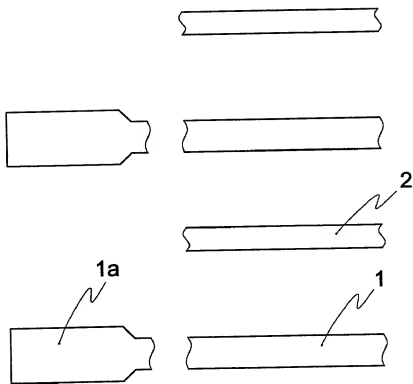


FIG. 17

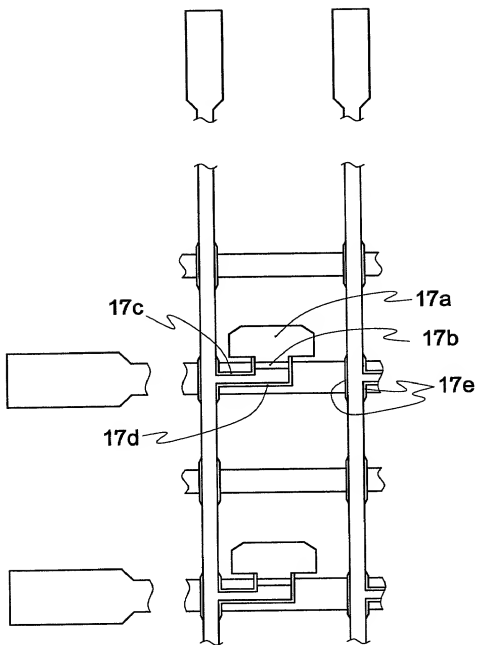


FIG. 18

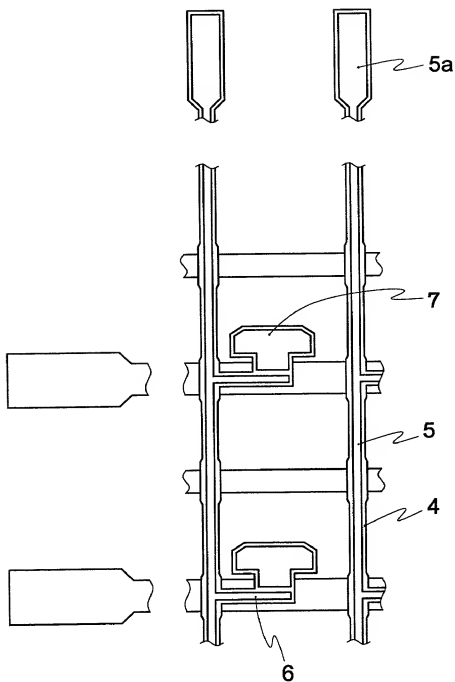


FIG. 19

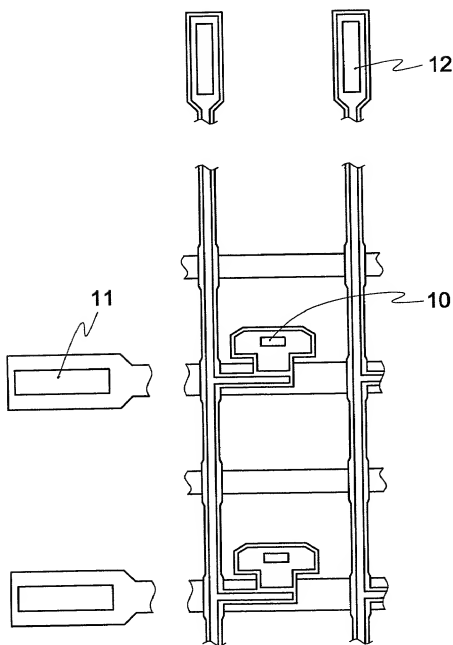


FIG. 20

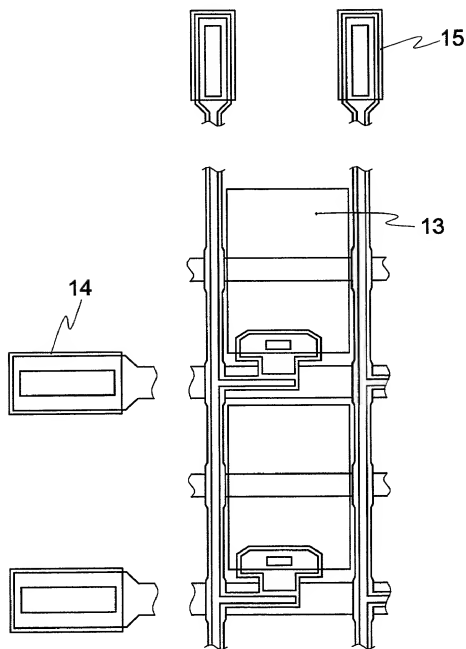


FIG. 21

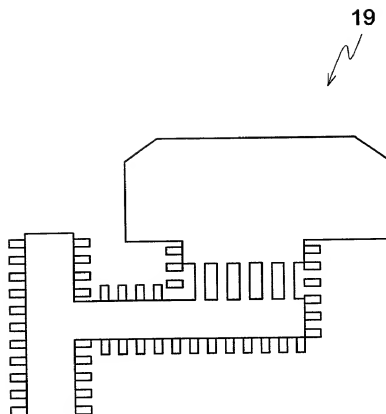




FIG. 22

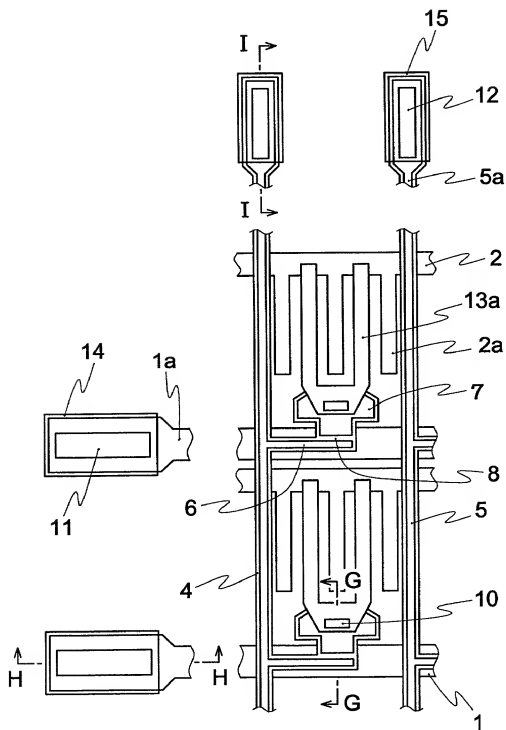


FIG. 23

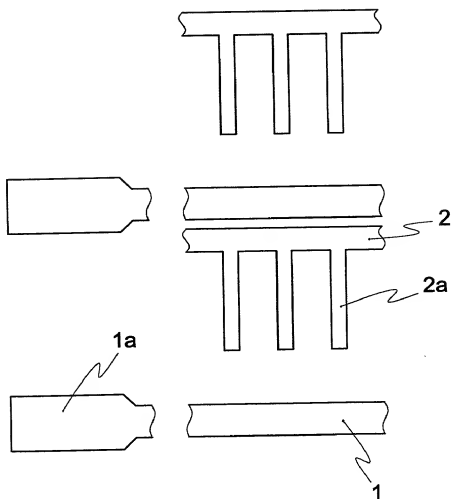


FIG. 24

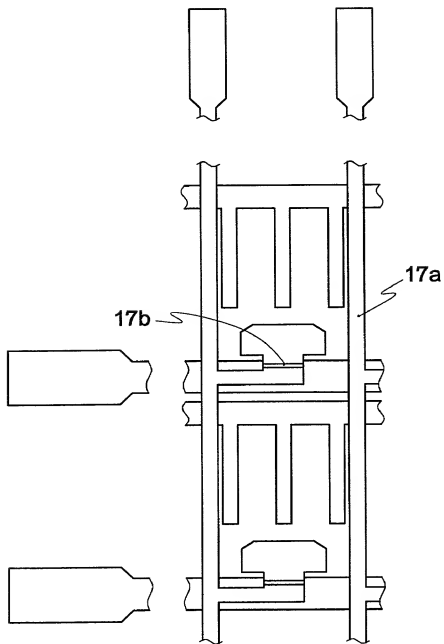


FIG. 25

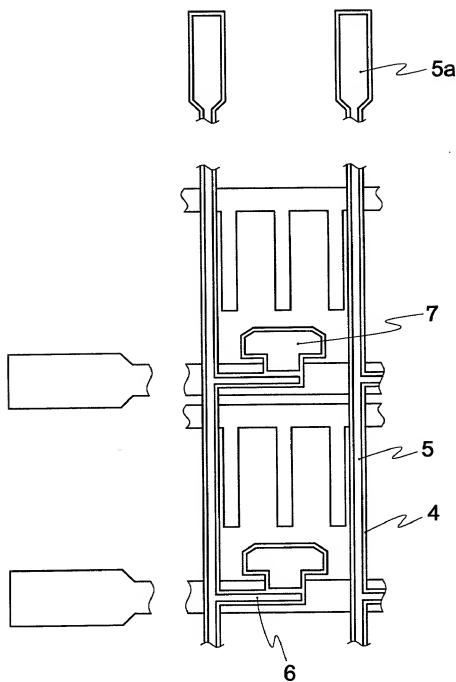


FIG. 26

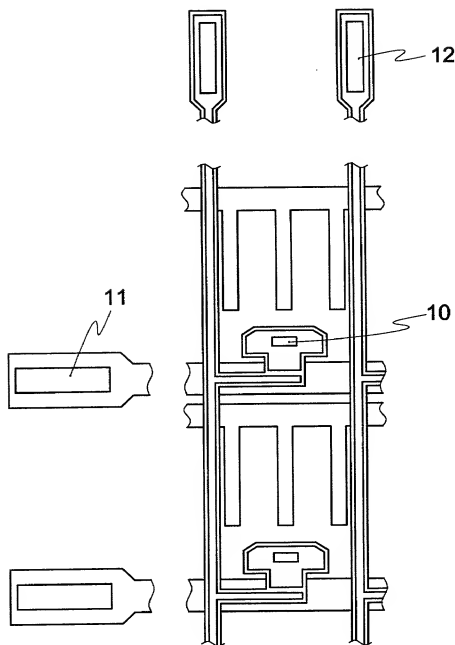


FIG. 27

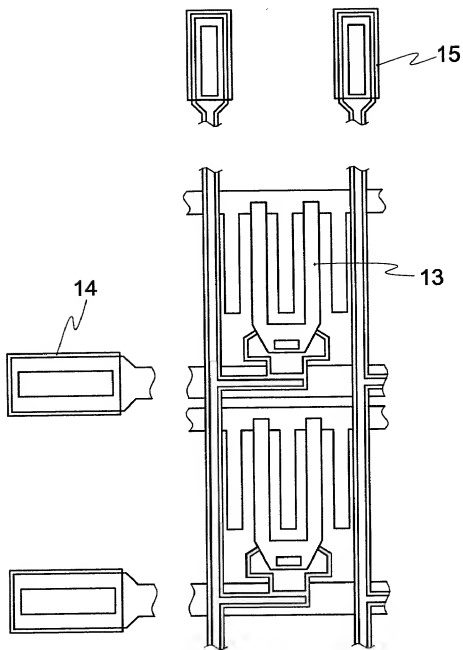


FIG. 28

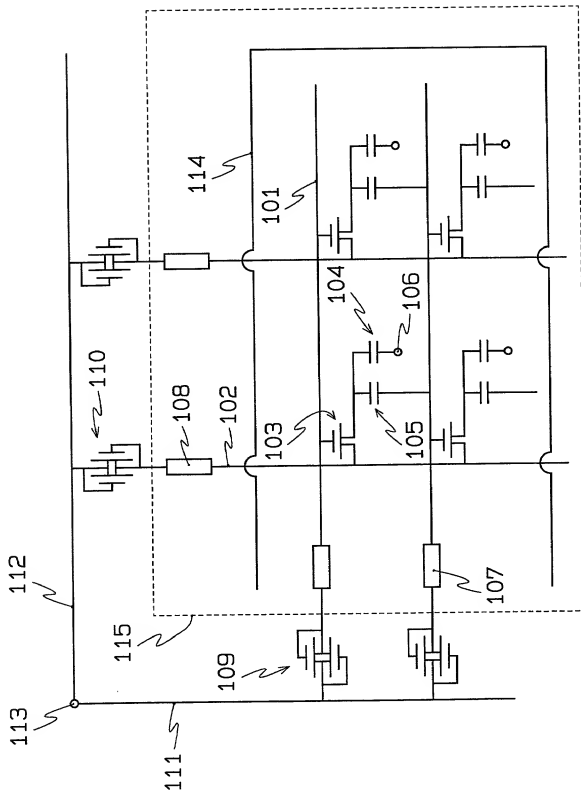


FIG. 29(a)

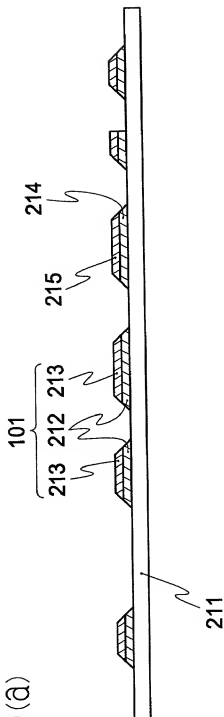


FIG. 29(b)

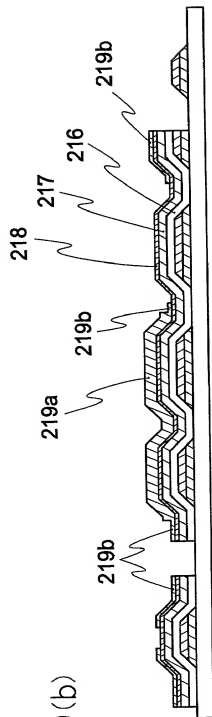




FIG. 30(a)

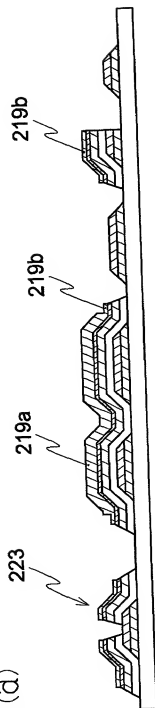


FIG. 30(b)

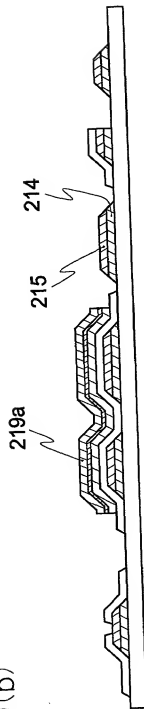


FIG. 31(a)

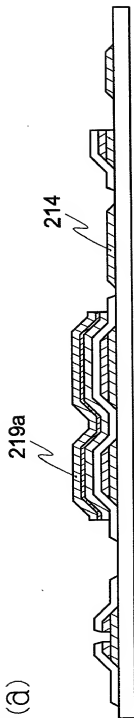


FIG. 31(b)

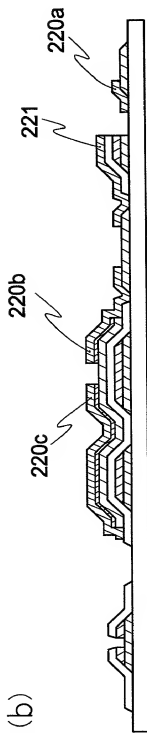


FIG. 31(c)

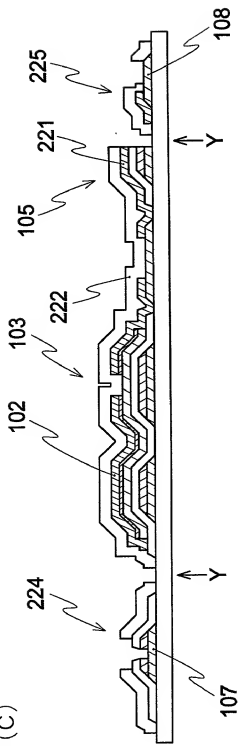


FIG. 32(a)

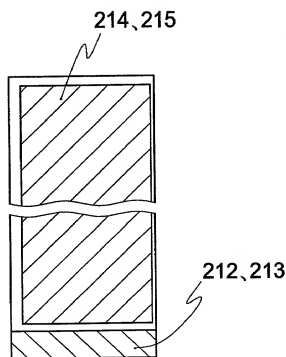


FIG. 32(b)

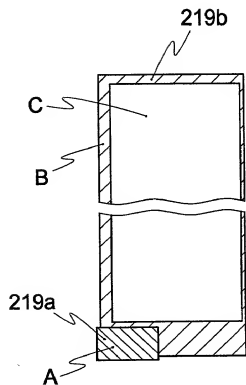


FIG. 32(c)

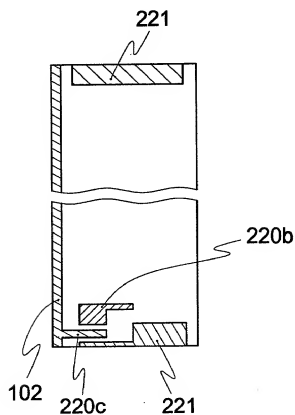


FIG. 32(d)

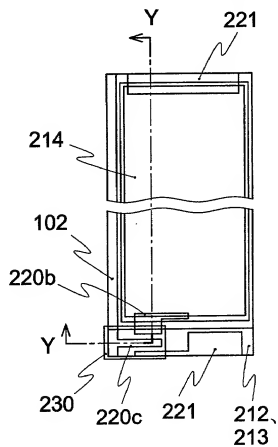


FIG. 33

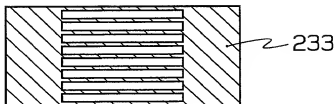


FIG. 34

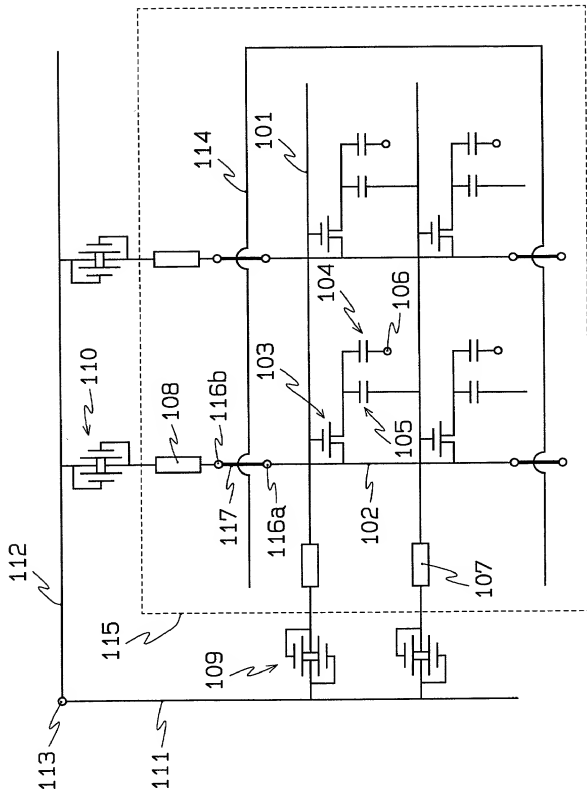
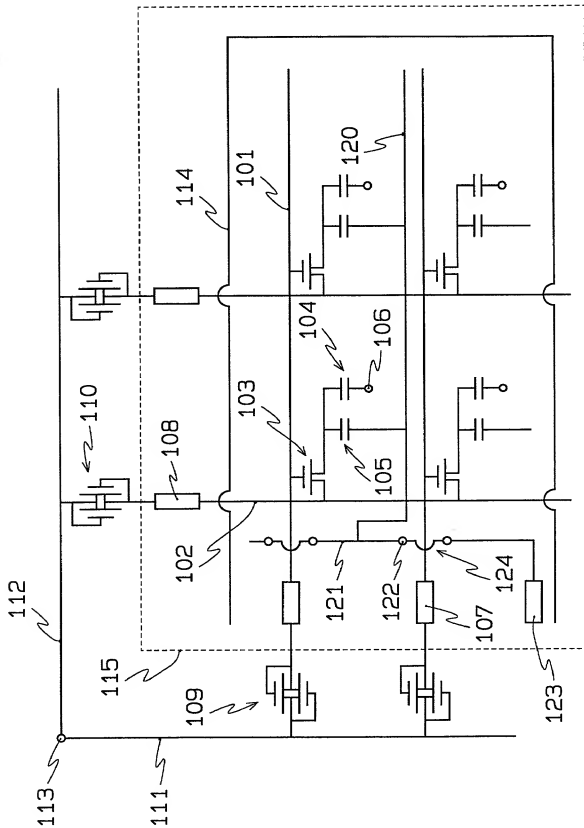


FIG. 35



2

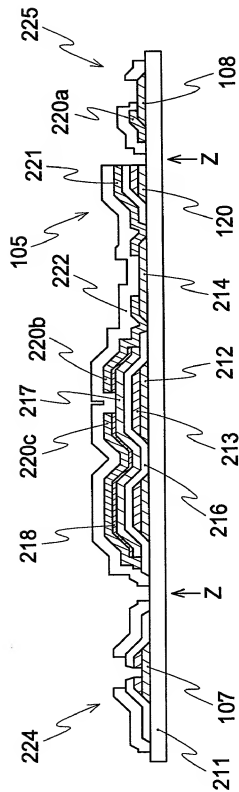


FIG. 37(a)

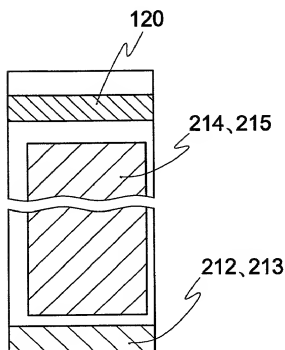


FIG. 37(b)

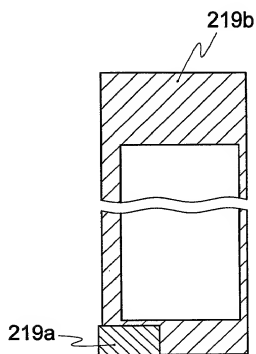


FIG. 37(c)

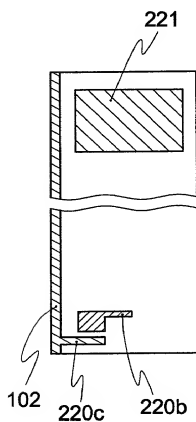


FIG. 37(d)

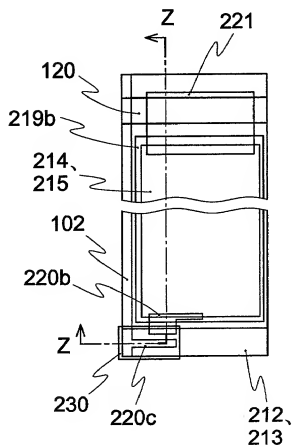




FIG. 38

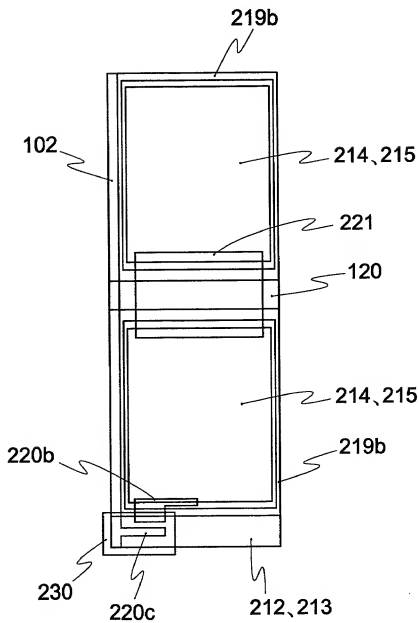


FIG. 39

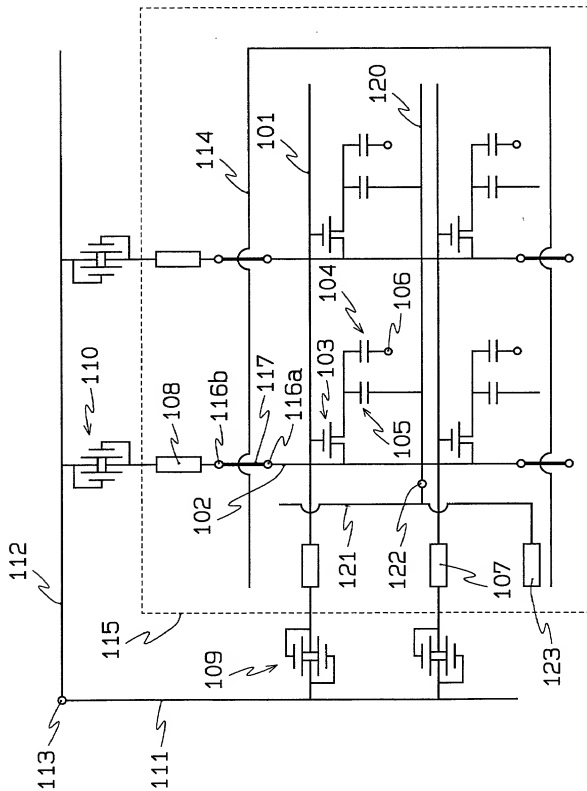


FIG. 40

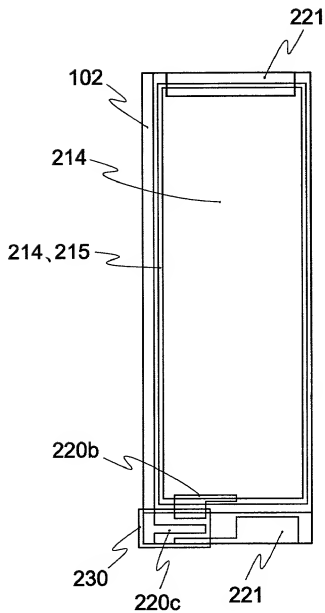


FIG. 41(a)

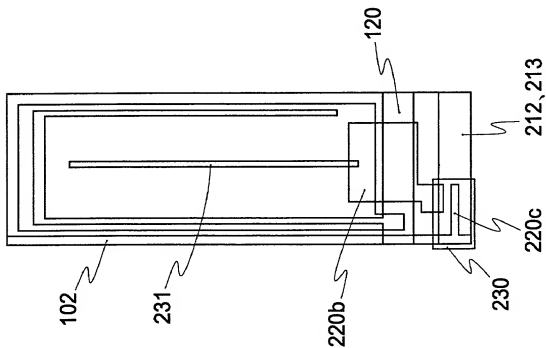


FIG. 41(b)

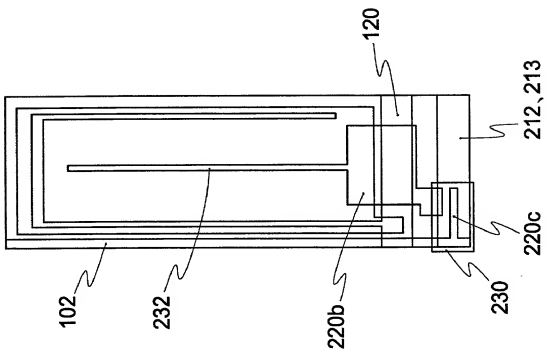


FIG. 42(a)

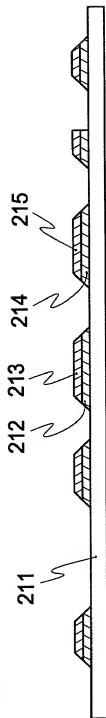


FIG. 42(b)

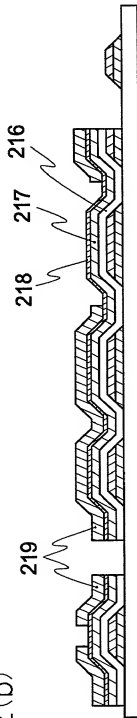


FIG. 42(c)

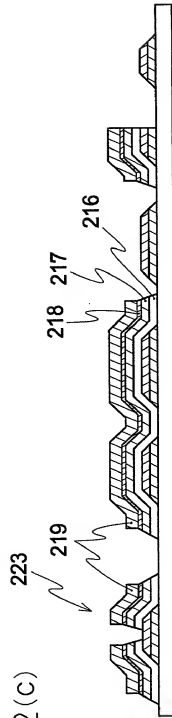


FIG. 43(a)

FIG. 43(a)

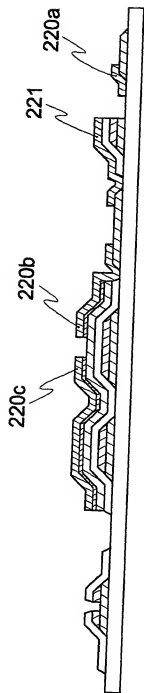


FIG. 43(b)

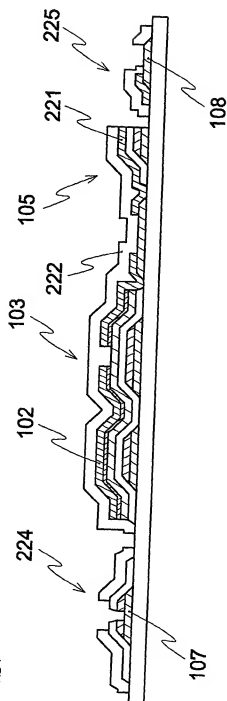


Figure 1(d) is a cross-sectional view of a substrate 410 with a thin layer 411 and a patterned layer 412.

This cross-sectional view shows a multi-layered structure. It features a base layer with a series of raised, stepped regions. The first raised region is labeled A1, the second is B1, and the third is C1. Each of these regions has a top surface labeled 418a. The structure is composed of several layers, with the topmost layer being a thin, textured layer labeled 413. Below this is a layer labeled 414, and the bottommost layer is labeled 415. The regions A1, B1, and C1 are separated by recessed areas.

A cross-sectional view of a semiconductor device. A substrate is shown with a patterned layer 418a and a contact layer 423.

FIG. 45(a)

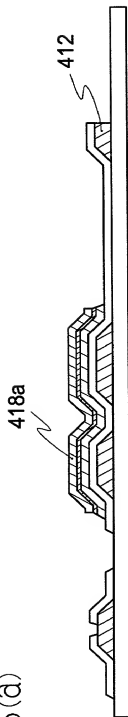


FIG. 45(b)

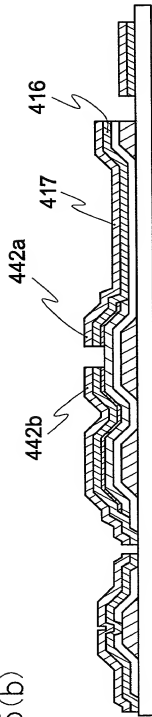


FIG. 45(c)

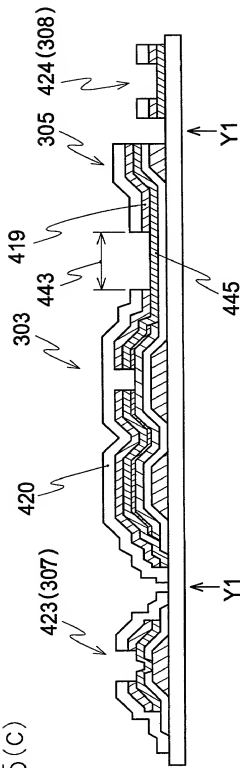




FIG. 46(a)

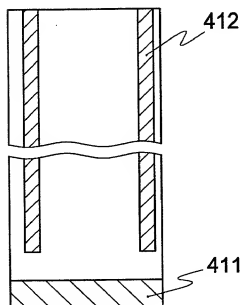


FIG. 46(b)

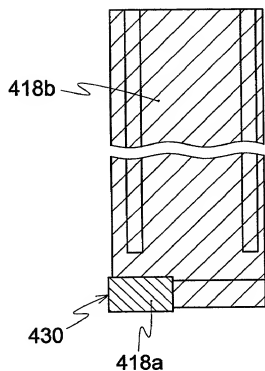


FIG. 46(c)

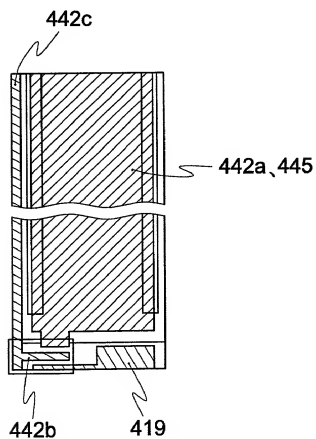


FIG. 47(a)

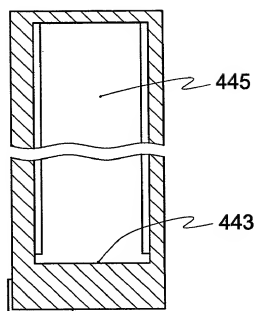


FIG. 47(b)

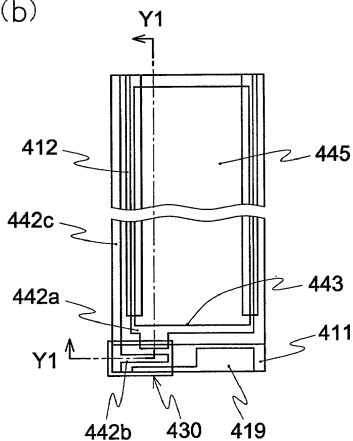


FIG. 48

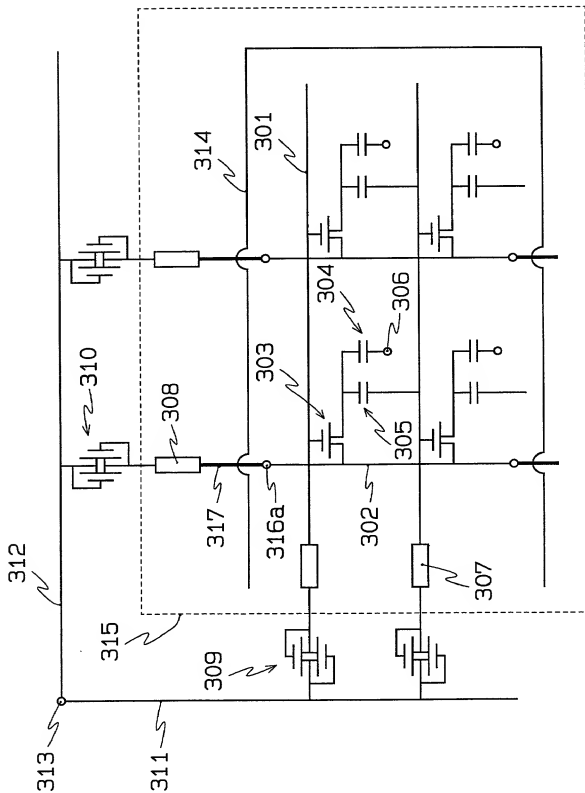


FIG. 49

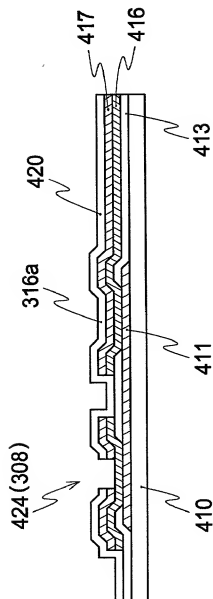


FIG. 50

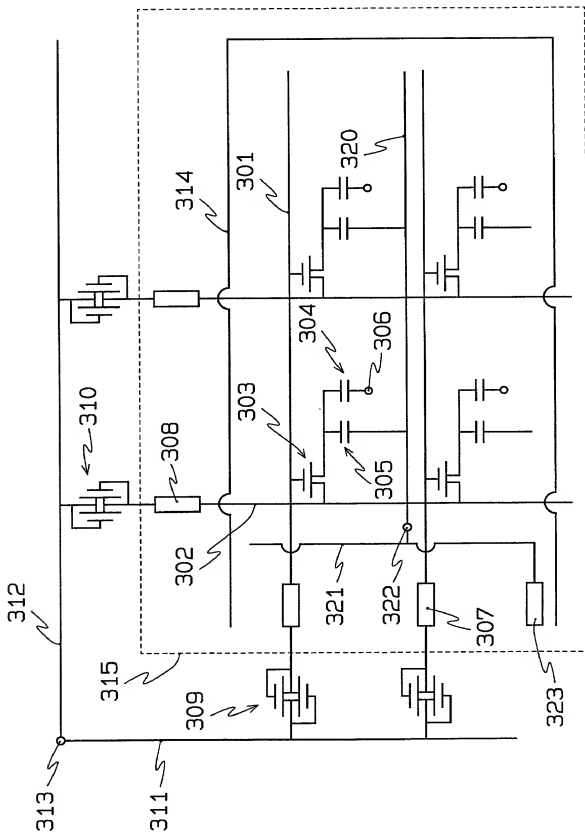


FIG. 51

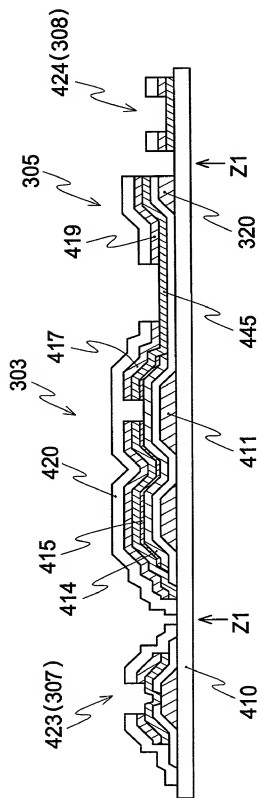


FIG. 52(a)

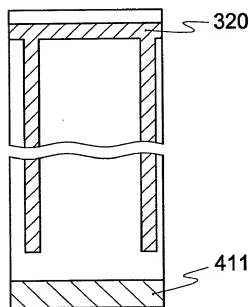


FIG. 52(b)

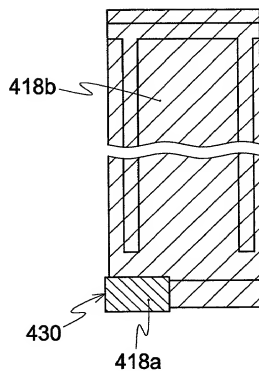


FIG. 52(c)

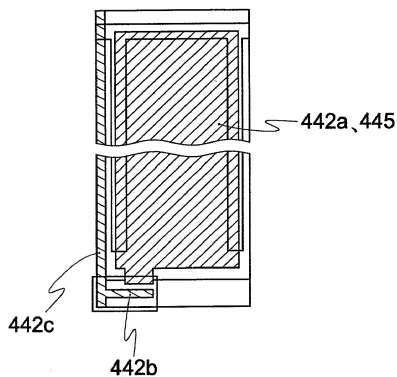


FIG. 53(a)

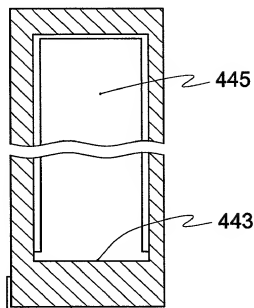
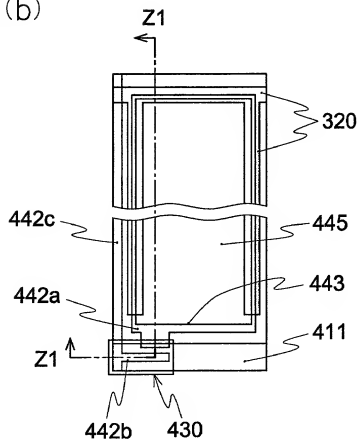


FIG. 53(b)





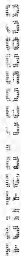
[illegible]

FIG. 55

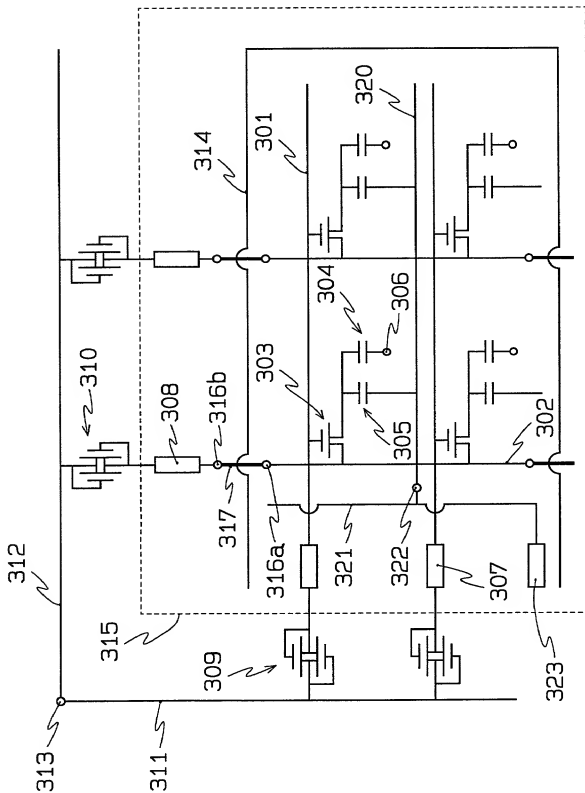


FIG. 56

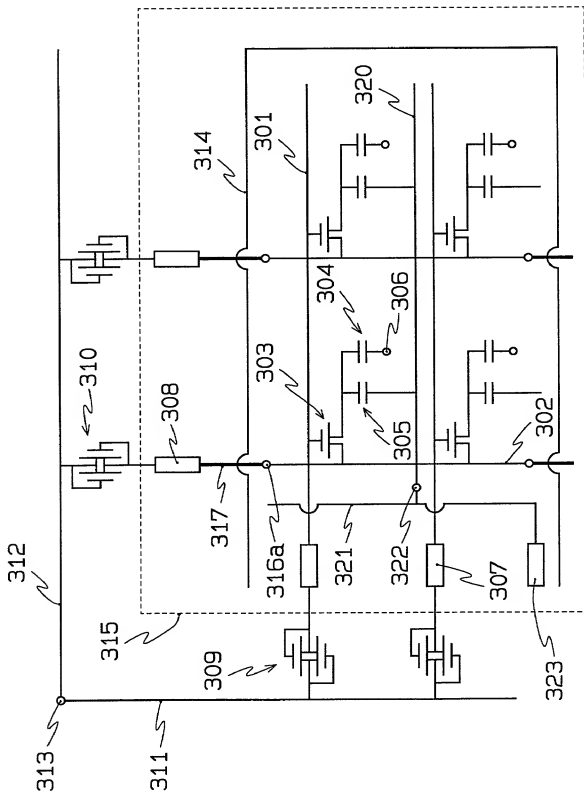


FIG. 57

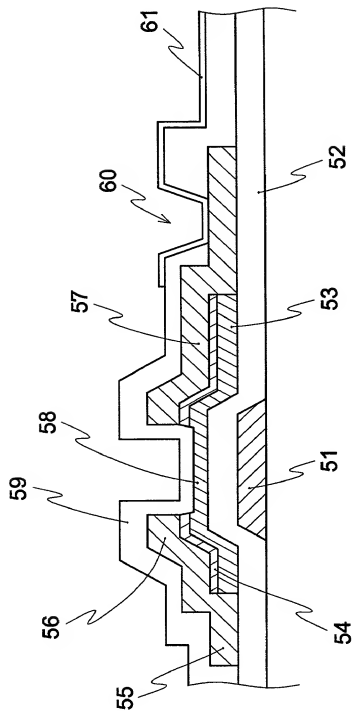


FIG. 58

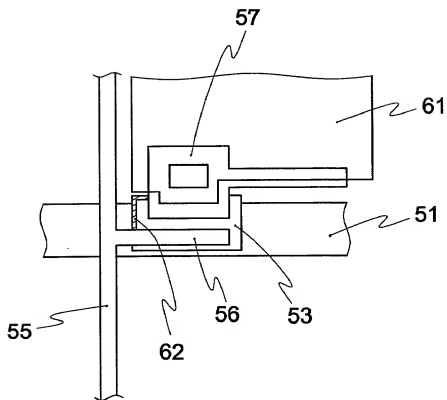


FIG. 59(a)



FIG. 59(b)

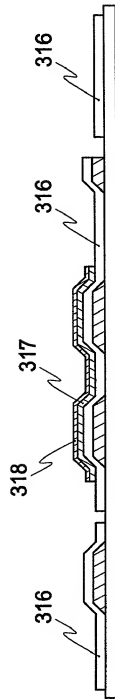


FIG. 59(c)

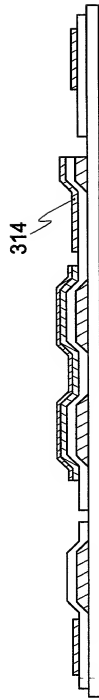


FIG. 60(a)

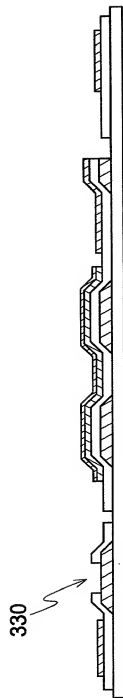


FIG. 60(b)

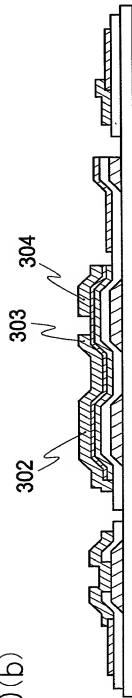


FIG. 60(c)

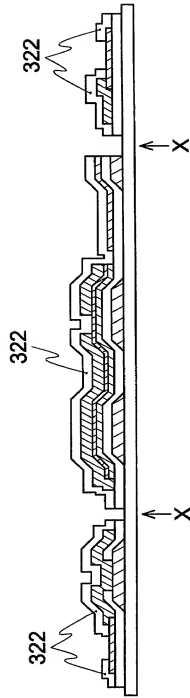


FIG. 61(a)

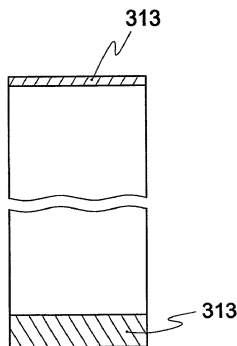


FIG. 61(b)

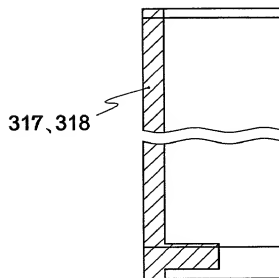


FIG. 61(c)

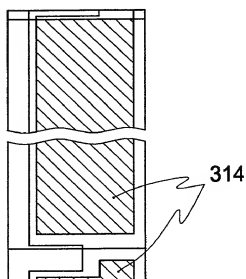


FIG. 61(d)

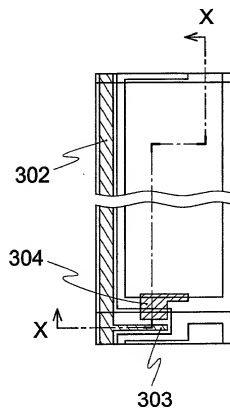




FIG. 62(a)

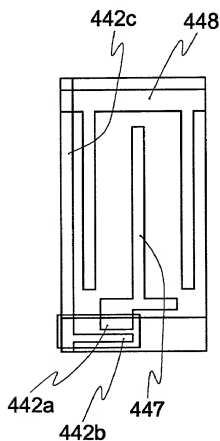


FIG. 62(b)

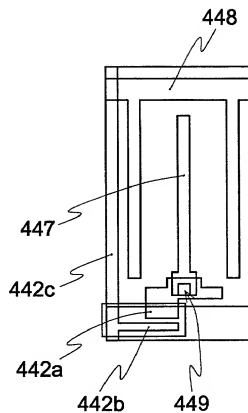


FIG. 62(c)

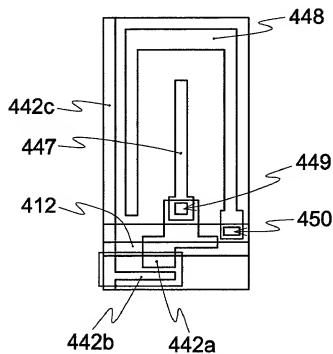


FIG. 63(a)

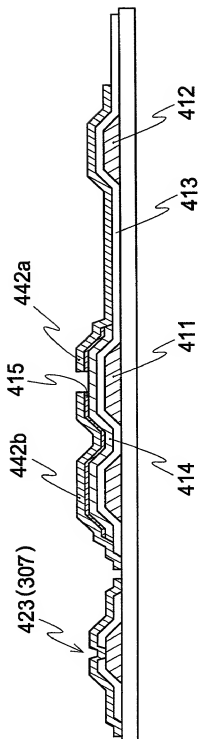


FIG. 63(b)

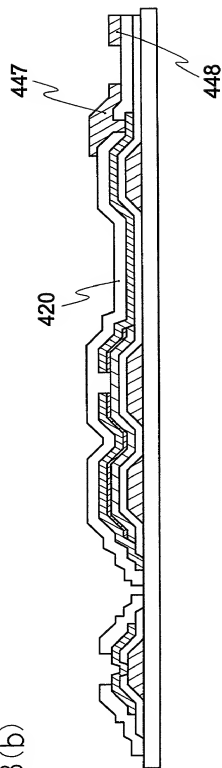


FIG. 64

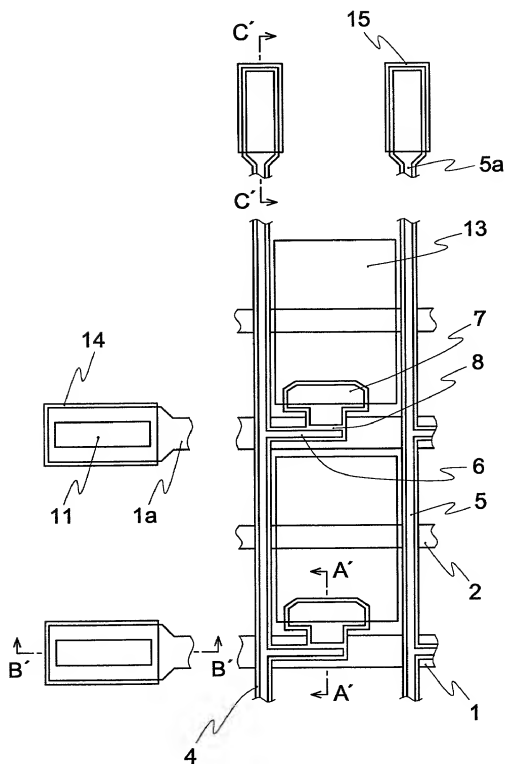


FIG. 65(a)

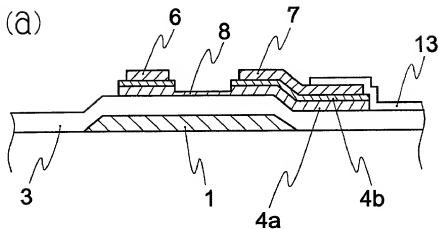


FIG. 65(b)

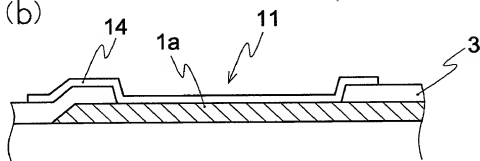


FIG. 65(c)

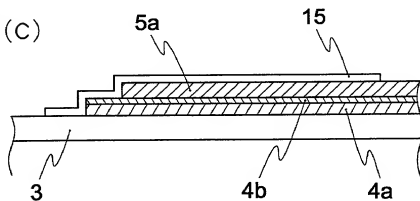


FIG. 65(d)

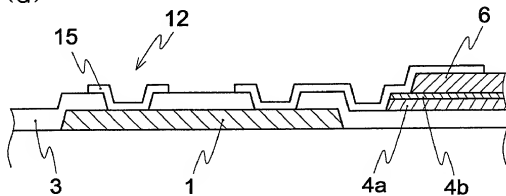


FIG. 66

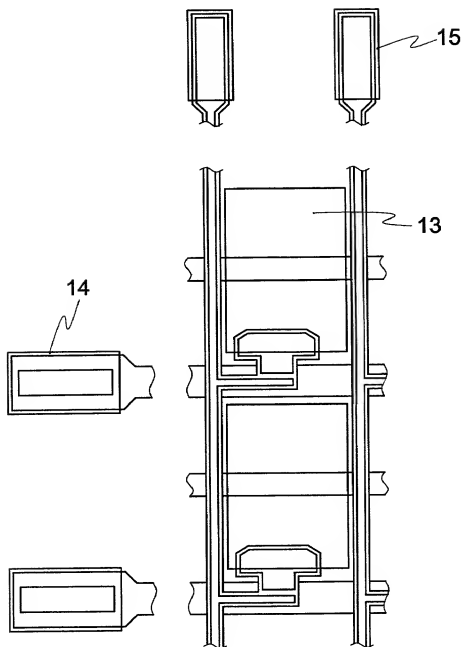


FIG. 67

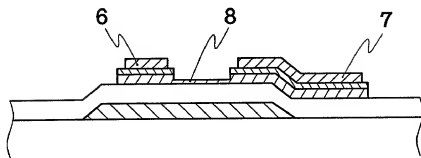


FIG. 68

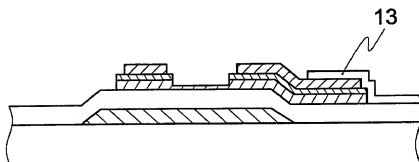


FIG. 69

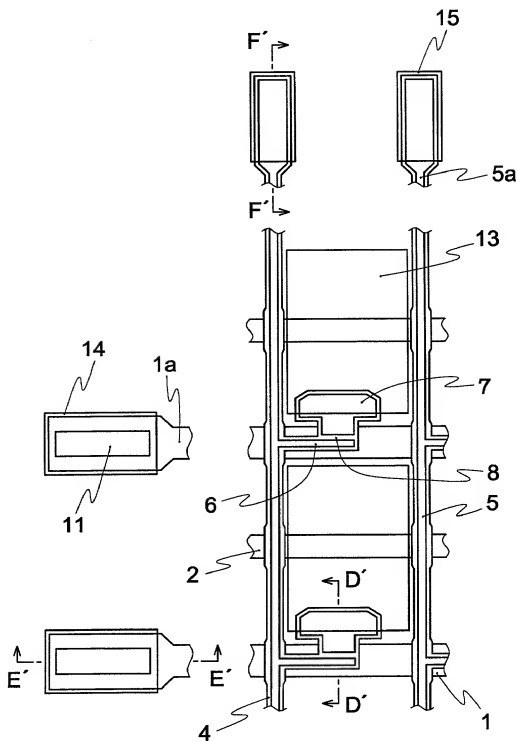


FIG. 70

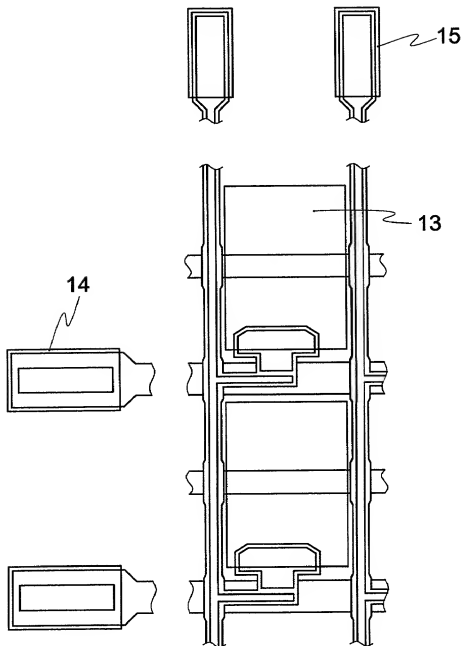




FIG. 71

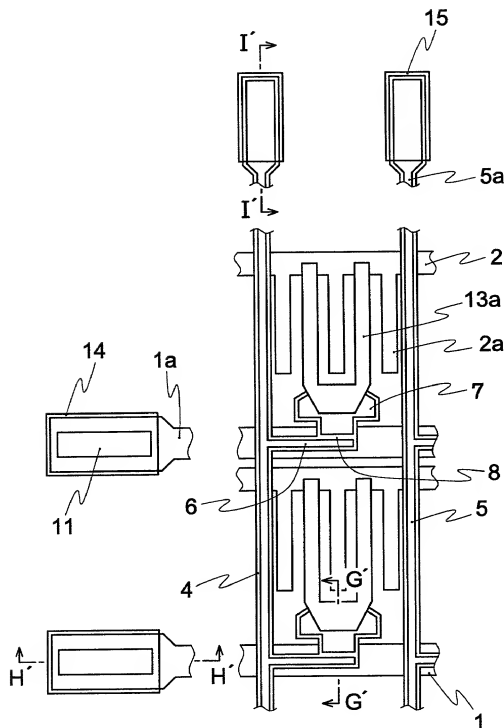


FIG. 72

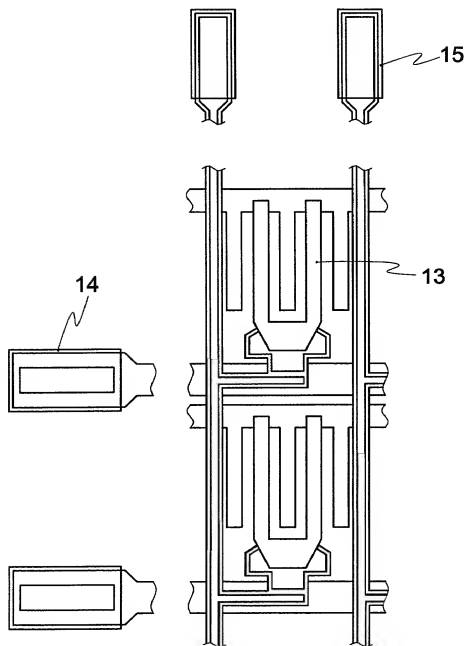


FIG. 73

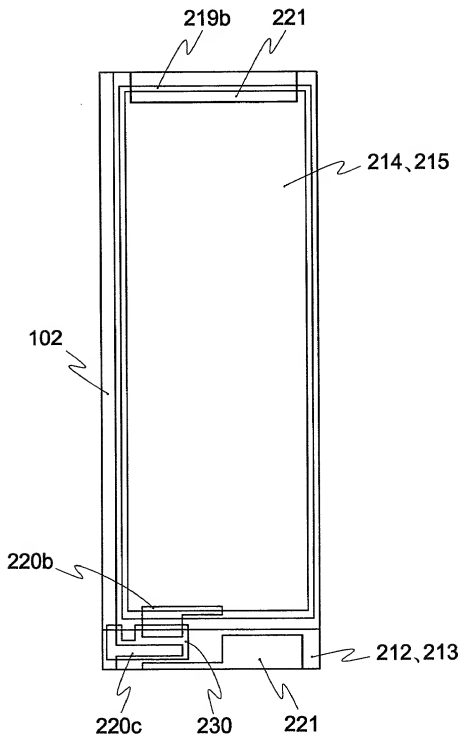


FIG. 74

